

Fig.1(A)

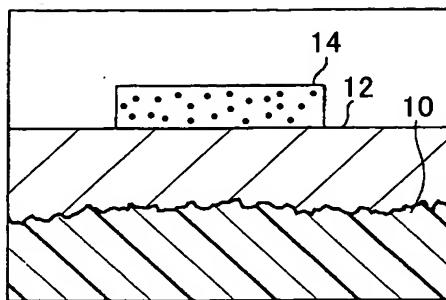


Fig.1(B)

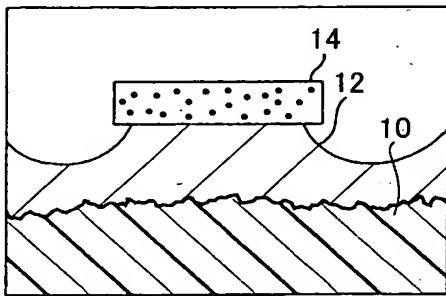


Fig.1(C)

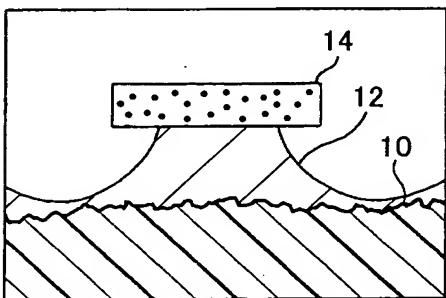


Fig.1(D)

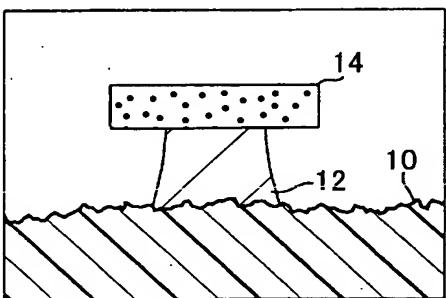


Fig.1(E)

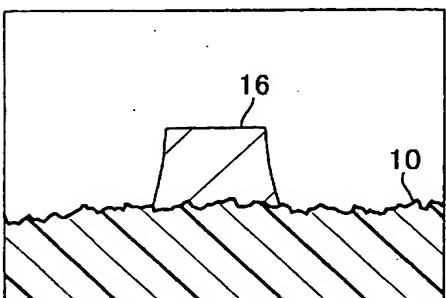


Fig.2(A)

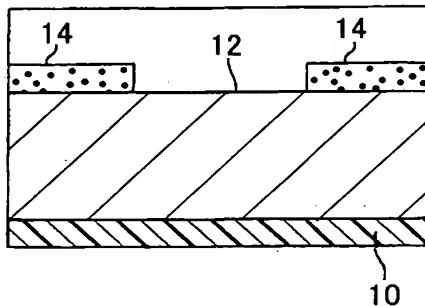


Fig.2(B)

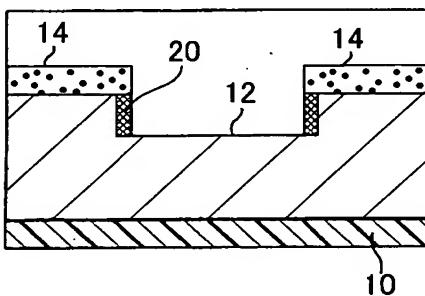


Fig.2(C)

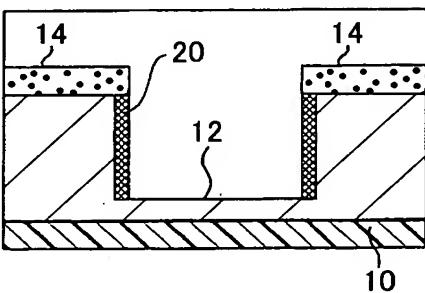


Fig.2(D)

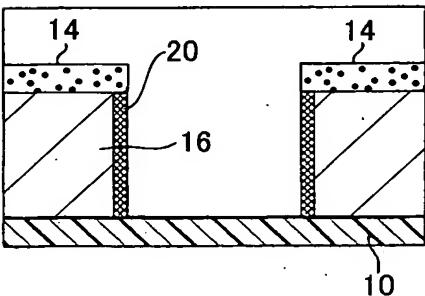


Fig.3(A)

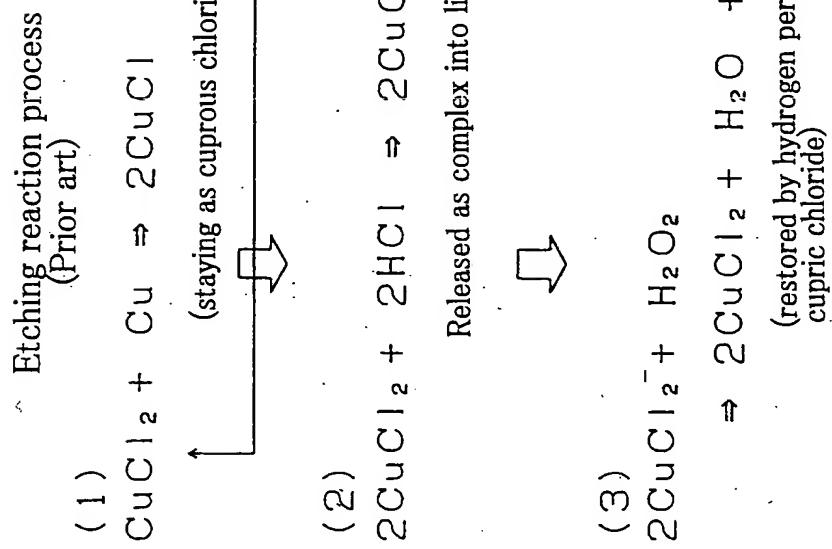


Fig.3(B)

Etching reaction process  
(Present invention)

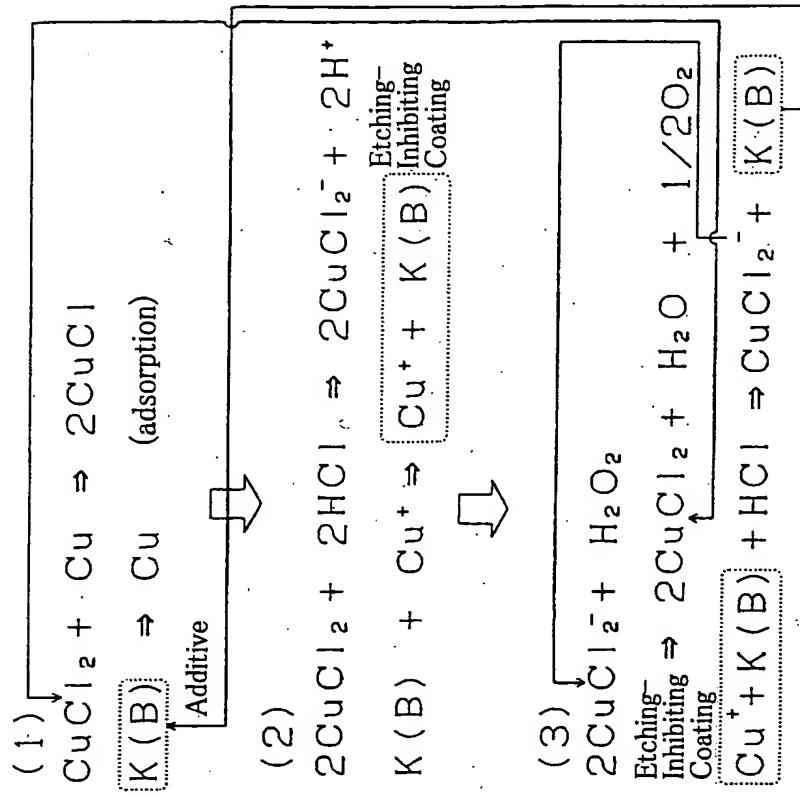


Fig.4(A) STRUCTURE

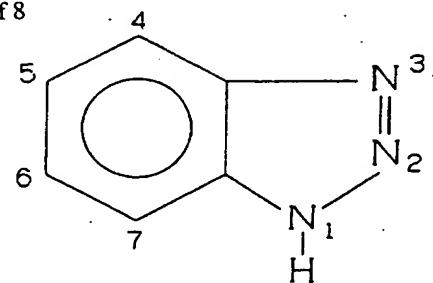


Fig.4(B) BTA

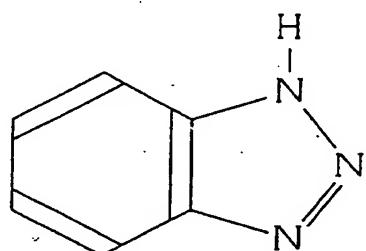


Fig.4(C) TTA

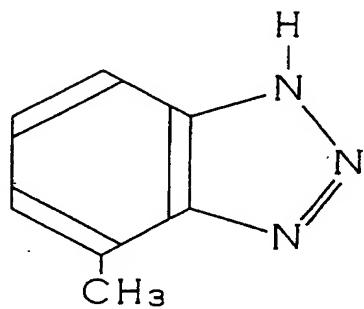


Fig.4(D) BTA-COOH

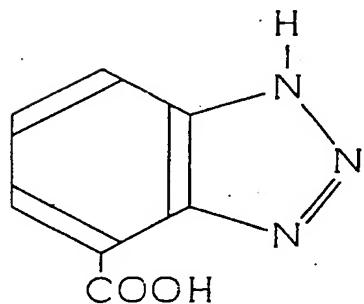


Fig. 5(A1)

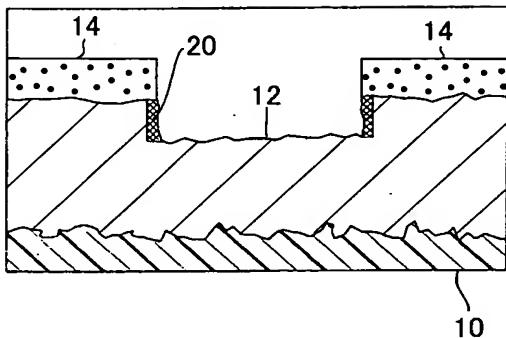


Fig. 5(B1)

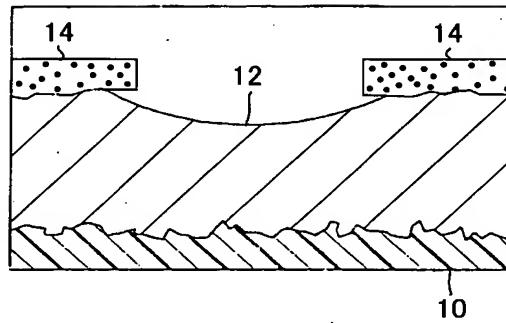


Fig. 5(A2)

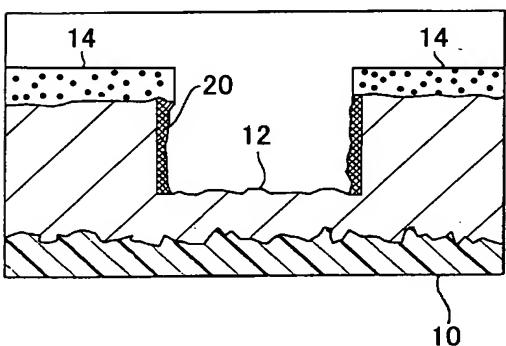


Fig. 5(B2)

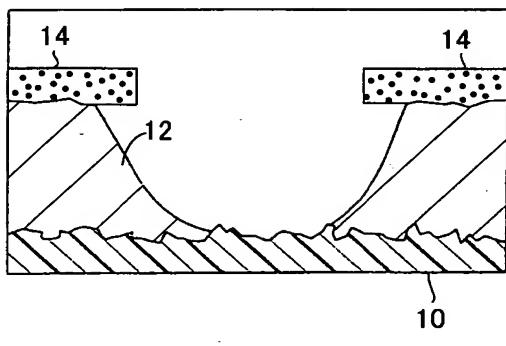


Fig. 5(A3)

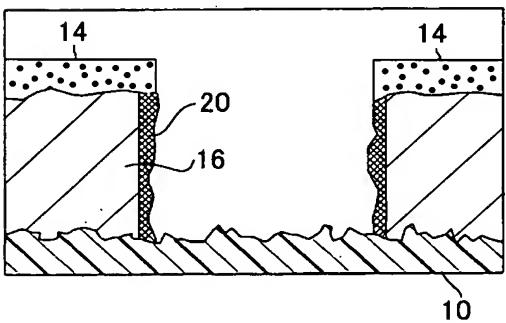


Fig. 5(B3)

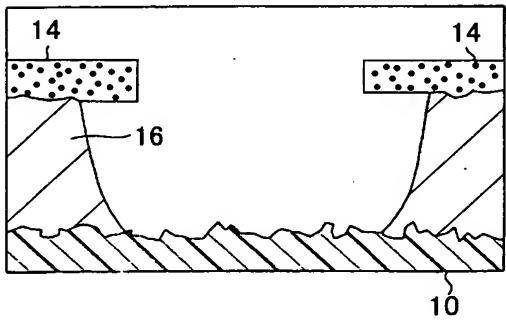


Fig. 6

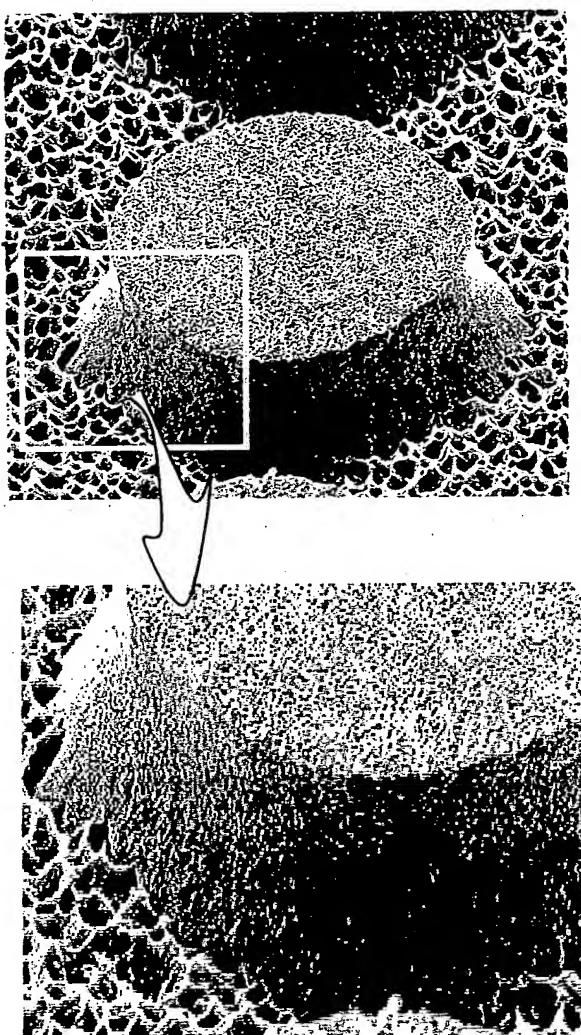
Configuration of wiring pattern  
(Prior art)

Fig. 7

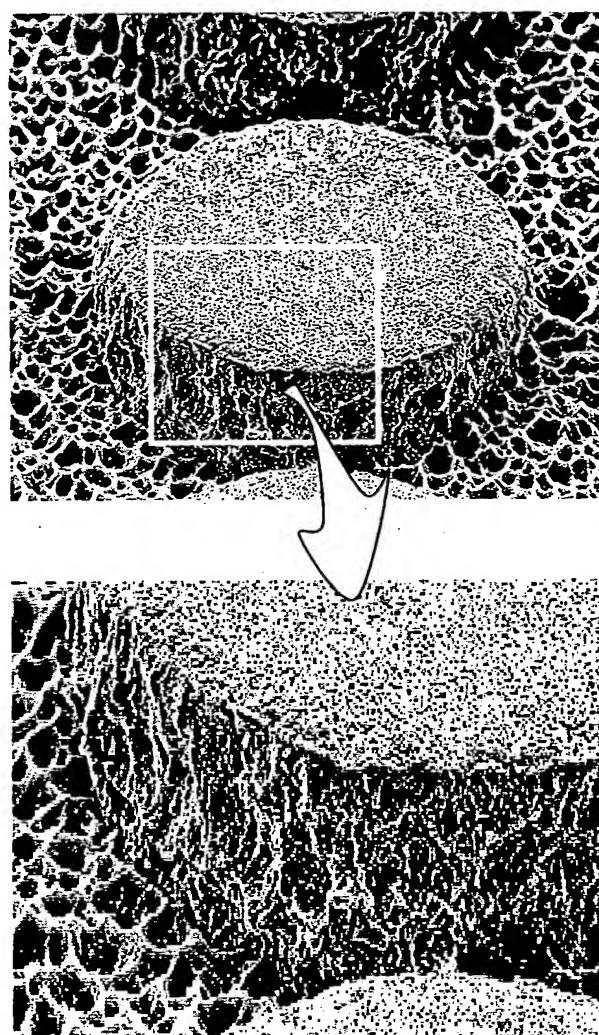
Configuration of wiring pattern  
(Present invention)

Fig. 8

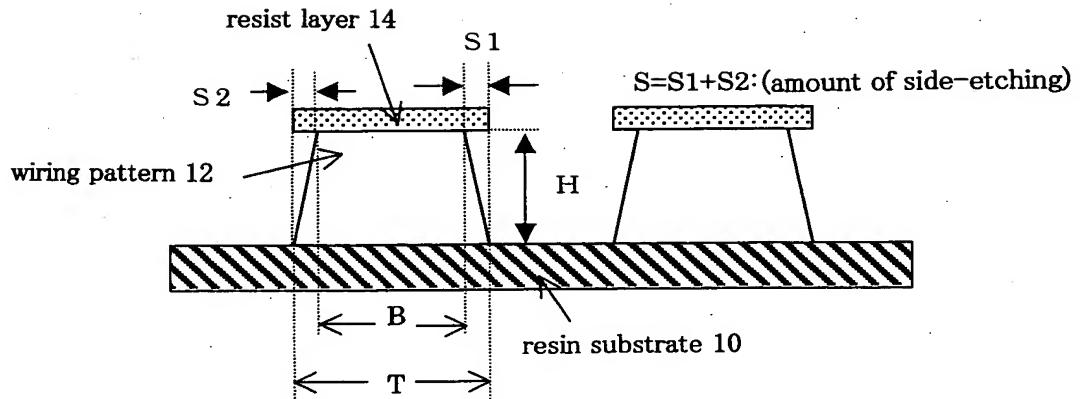


Fig. 9(A) (After etching)

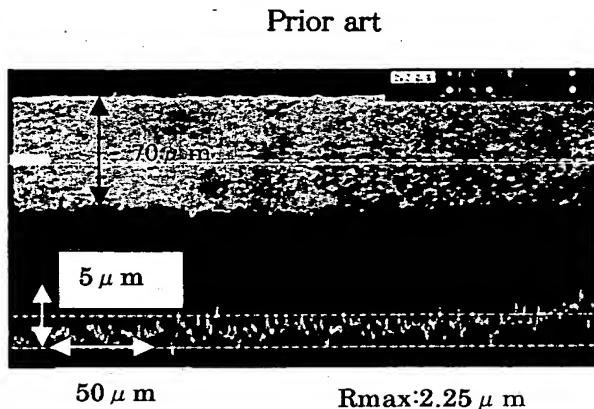


Fig. 10(A) (After etching)

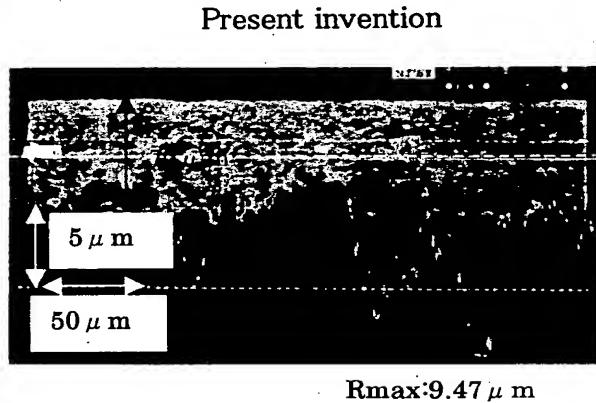


Fig. 9(B) (After CZ roughing processing)

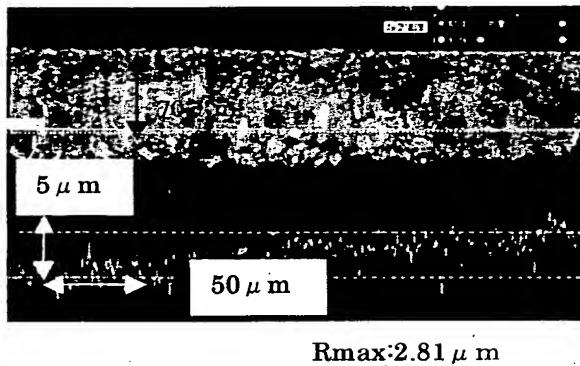


Fig. 10(B) (After CZ roughing processing)

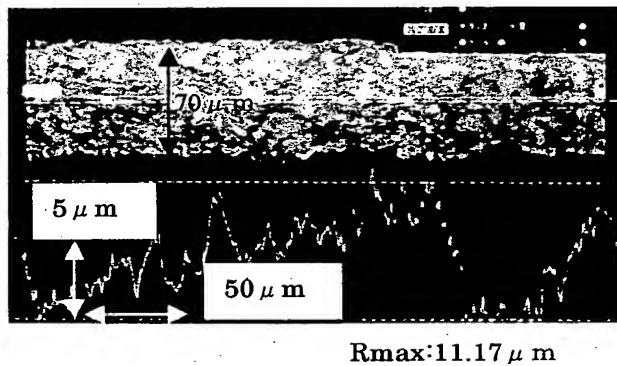


Fig. 9(C) (After blackening process)

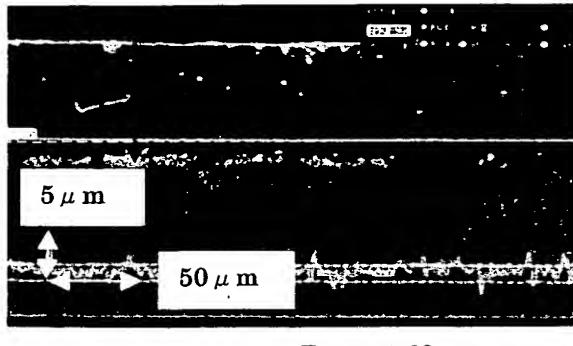


Fig. 10(C) (After blackening process)

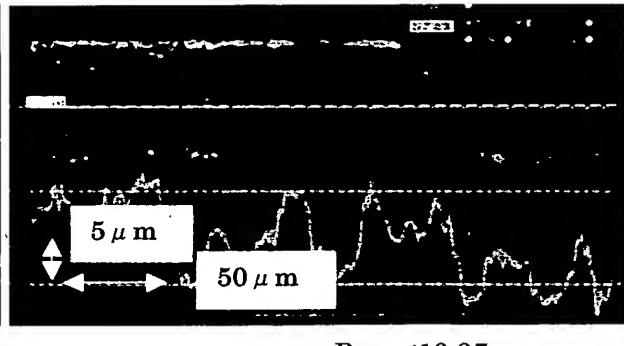


Fig. 11

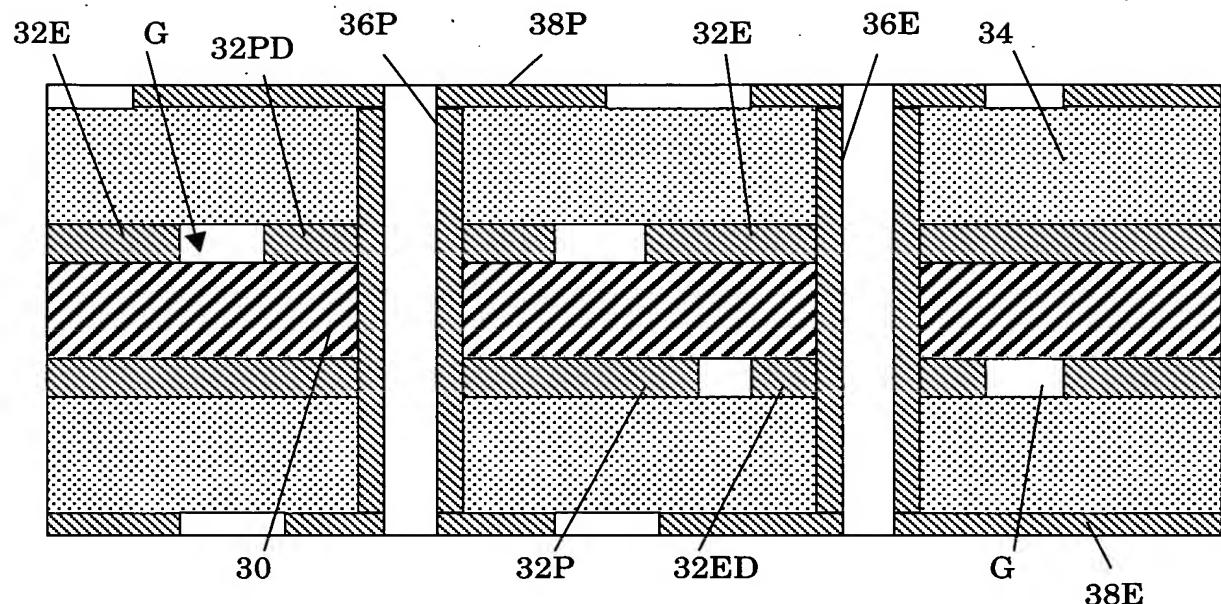


Fig. 12 (A)

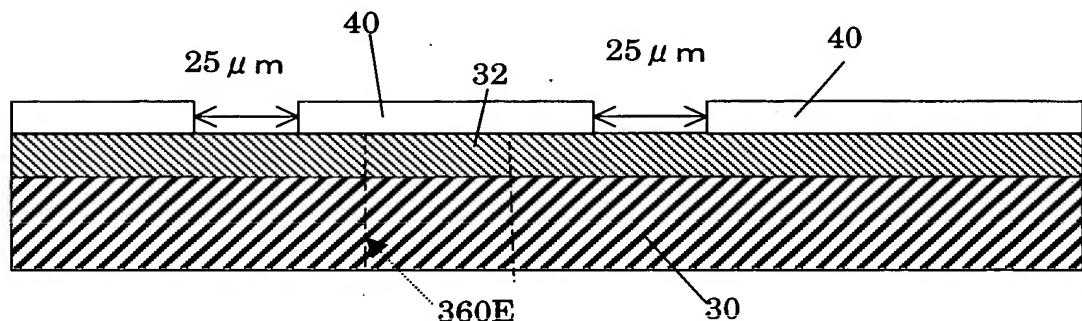


Fig. 12 (B)

